



Click [here](#) for the 3D model.

### Dimensions

Case Code	6D
L	8mm +/-0.38mm
W	8.9mm +/-0.2mm
H	9.2mm +/-0.38mm
S	1.9mm +/-0.38mm
F	7.4mm +/-0.2mm
K	7.7mm +/-0.38mm

### Packaging Specifications

Packaging	Tray
Packaging Quantity	50

### General Information

Series	TSP
Dielectric	Polymer Tantalum
Style	Stacked Chip
Description	SMD, Polymer, KO, Stacks, High Reliability
Features	High Reliability
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
SCIP Number	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination	Solder Coated
Termination (Stack)	Silver Plated
AEC-Q200	No
MSL	3

### Specifications

Capacitance	1,300 uF
Capacitance Tolerance	20%
Voltage DC	10 VDC (105C), 6.7 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
Resistance	5 mOhms (100kHz 25C)
Leakage Current	1320 uA (5min 25°C)
Testing and Reliability	4 Cycles At +25C +/-5C